Instructions to Vendor of Mother Boards

1. The total number of finished boards for each of the four patterns is to be 284.

2. An extra quantity of 5% on all parts should be purchased and returned to the University of Chicago at the conclusion of the contract. These will be used for future maintenance.

3. The vendor is responsible for parts procurement, PCB fabrication, and component mounting.

4. Parts are to be purchased according to the type and manufacturer specified in the parts order list. Any substitutions must be approved by H. Sanders of the University of Chicago.

5. The PC boards should be fabricated with FR4 material having a minimum transition temperature of 150˚C.

6. Prior to assembly, the PC boards should be 100% tested for shorts and continuity according to the supplied net list.

7. The University of Chicago has volume pricing agreements with Wiley Electronics for Altera and Comlinear components. Wiley should be one of the bidders for parts and the RFQ should mention the University of Chicago. The contact at Wiley is Michael Camizzo at 630-620-0969.

8. The Altera parts are moisture sensitive. Procedures indicated on the packaging material should be followed, including if necessary baking prior to mounting.

9. Prior to the start of volume production of each of the four patterns a set of 5 cards should be completed and shipped to the University of Chicago for testing and approval. Production should be placed in a hold status until these tests are complete and satisfactory. This step will require fully-assembled cards to be at the university for 2 days.

10. For quality control during the volume production, 1 card should be removed from assembly stream each hour. It should be equipped with serial number bar-code labels supplied by the University of Chicago and a record made in the production log of the serial number, date and time of production, operator, and machine. These cards should be shipped by "next-day air" to the University of Chicago each day, together with a copy of the production log.

Shipping address:

Electronics Development Group
Enrico Fermi Institute
University of Chicago
5641 S. Ingleside Ave.
Chicago, IL 60637

Contact:
Mr. Harold Sanders, Head of Engineering
773-702-7801